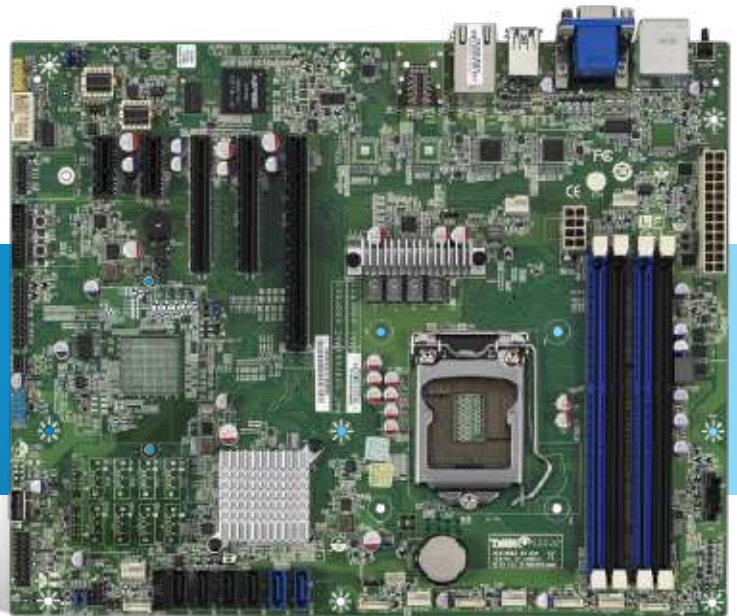


## SINGLE SOCKET ATX EMBEDDED PLATFORM

### S5532-HE

S5532G2NR-HE



### High-end single Embedded Application

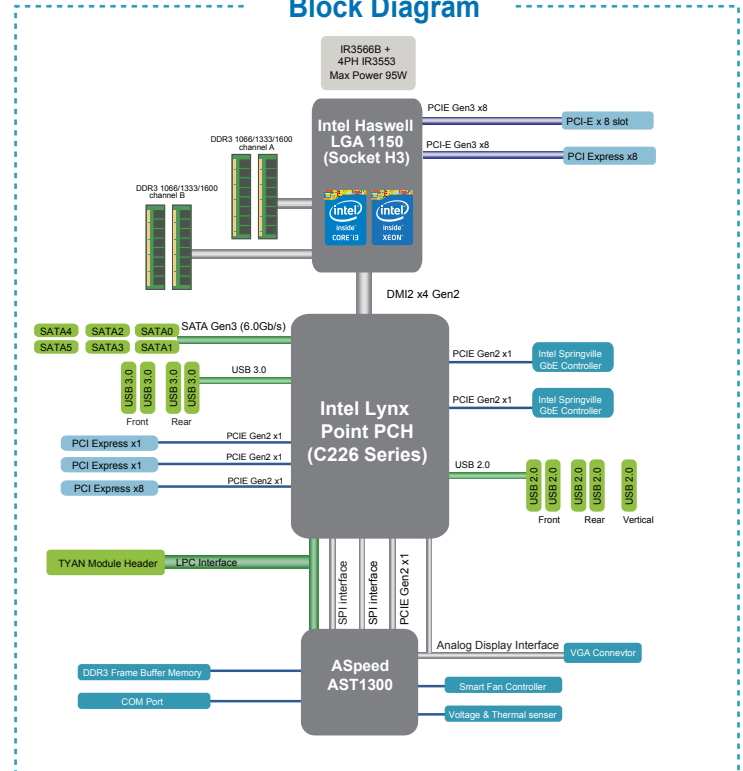
- Single LGA1150 socket support (1) Intel® Xeon® E3-1200 v3 & 4th Gen. Core i3 series processors
- Intel® C226
- (4) 240-pin DDR3 DIMM slots support up to 32GB unbuffered ECC DDR3 1600/1333/1066
- (1) PCI-E Gen.3 x16 slot (w/ x8 link)
  - (1) PCI-E Gen.3 x8 slot
  - (1) PCI-E Gen.2 x8 slot (w/ x1 link)
  - (2) PCI-E Gen.2 x4 slot (w/ x1 link)
- (6) SATA-III connectors running at 6.0Gb/s w/RAID 0/1/10/5 (Intel® RST)
- (2) GbE (via Intel® I210)
- ATX 12" x 9.6" (305 x 243.5mm)

# S5532-HE

S5532G2NR-HE

Processor	Supported CPU Series	Intel® Xeon® E3-1200 v3 & 4th Gen. Core i3 series processors	
	Socket Type / Q'ty	LGA 1150/ (1)	
	Thermal Design Power (TDP) wattage	Max up to 95W	
Chipset	PCH / PCI-E Switch	Intel® C226	
	Super I/O	-	
Memory	Supported DIMM Qty	(4) DIMM slots	
	DIMM Type / Speed	Unbuffered ECC DDR3 1600/1333/1066	
	Capacity	Up to 32GB	
	Memory voltage	1.5V	
Expansion Slots	PCI-E	(1) PCI-E Gen.3 x16 slot (w/ x8 link) (1) PCI-E Gen.3 x8 slot (1) PCI-E Gen.2 x8 slot (w/ x1 link) (2) PCI-E Gen.2 x4 slot (w/ x1 link)	
	PCI	-	
LAN	Port Q'ty	(2) GbE ports	
	Controller	Intel® I210	
	PHY	-	
	Controller	-	
Storage	SATA	Connector	(6) SATA
		Controller	Intel® C226
		Speed	(6) 6.0 Gb/s
		RAID	RAID 0/1/10/5 (Intel® RST)
Graphic	Connector type	D-Sub 15-pin	
	Chipset	Aspeed AST1300	
Audio	Chipset	-	
	Version	-	
Input /Output	USB	(4) USB3.0 ports (2 at rear, 2 via cable) / (5) USB2.0 ports (1 stack-up ports, 1 type A header, 2 via cable)	
	COM	(1) DB-9 COM Connector (at rear, COM1) + (1) Header (COM2)	
	Audio	-	
	VGA	(1) D-Sub 15-pin VGA port	
	DVI	-	
	Display Port	-	
	RJ-45	(2) GbE ports	
	SAS	-	
	Front Panel	(1) 2x12-pin SSI front panel header	
	SATA	(6) SATA-III connectors	
	System Monitoring	Chipset	Aspeed AST1300
Voltage		Monitors voltage for CPU, memory, chipset & power supply	
Fan		Total (4) 4-pin headers	
Temperature		Monitors temperature for CPU & system environment	

## Block Diagram



BIOS	Brand / ROM size	AMI / 16MB
	Feature	Plug and Play (PnP) /PCI2.3 /WfM2.0 /SMBIOS2.3 /PXE boot / User-configurable H/W monitoring / Auto-configurable of hard disk types / ACPI 3.0/ACPI sleeping states S3,S4,S5
Form Factor	Form Factor	ATX
	Board Dimension	12"x9.6" (305x243.8mm)
Operating System	OS supported list	Please refer to our Intel OS supported list.
Regulation	FCC (DoC)	Class A
	CE (DoC)	Yes
Operating Environment	Operating Temp.	10° C ~ 35° C (50° F~ 95° F)
	Non-operating Temp.	- 40° C ~ 70° C (-40° F ~ 158° F)
	In/Non-operating Humidity	90%, non-condensing at 35° C Non-operating Relative Humidity: 10% to 95% (non-condensing)
RoHS	RoHS 6/6 Compliant	Yes

(Specifications are subject to change without notice. Items pictured may only be representative.)

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